PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY

CONVEYING PARTY DATA

Name	Execution Date
UBS AG, Stamford Branch	09/30/2010

RECEIVING PARTY DATA

Name:	ISOLA USA Corp.
Street Address:	3100 West Ray Road, Suite 301
City:	Chandler
State/Country:	ARIZONA
Postal Code:	85226

PROPERTY NUMBERS Total: 69

Property Type	Number
Patent Number:	4501787
Patent Number:	4665154
Patent Number:	4767643
Patent Number:	4789770
Patent Number:	4806596
Patent Number:	5142151
Patent Number:	5160567
Patent Number:	5334696
Patent Number:	5350621
Patent Number:	5387656
Patent Number:	5457319
Patent Number:	5464658
Patent Number:	5508328
Patent Number:	5512381
Patent Number:	5626774

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Patent Number:	6083855
Patent Number:	6168898
Patent Number:	6187852
Patent Number:	6242078
Patent Number:	6255039
Patent Number:	6322885
Patent Number:	6440567
Patent Number:	6509414
Patent Number:	6658375
Patent Number:	7090924
Patent Number:	7255927
Patent Number:	7425371
Patent Number:	7507471
Patent Number:	7521494
Patent Number:	4853423
Patent Number:	4975319
Patent Number:	5162450
Patent Number:	5073605
Patent Number:	5141791
Patent Number:	5096771
Patent Number:	5098781
Patent Number:	5262491
Patent Number:	5108842
Patent Number:	5213886
Patent Number:	5362534
Patent Number:	5437914
Patent Number:	5557843
Patent Number:	5779870
Patent Number:	5670250
Patent Number:	5545466
Patent Number:	5626804
Patent Number:	6618238
Patent Number:	6584820
Patent Number:	6609294
Patent Number:	6436276

Patent Number:	6403229
Patent Number:	6632511
Patent Number:	6955740
Patent Number:	6768316
Patent Number:	7687556
Patent Number:	5292557
Application Number:	09928103
Application Number:	10310418
Application Number:	10314602
Application Number:	10858344
Application Number:	11002045
Application Number:	10952102
Application Number:	11269132
Application Number:	11634471
Application Number:	11637222
Application Number:	07994003
Application Number:	11230318
Application Number:	07958625
Application Number:	08084694

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	244130/1195
NAME OF SUBMITTER:	Elaine D. Ziff

Total Attachments: 7
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RELEASE OF SECURITY INTEREST IN PATENT COLLATERAL

This RELEASE, dated as of September___, 2010 (this "Release"), is made by UBS AG, Stamford Branch, as Collateral Agent ("Collateral Agent"), in favor of ISOLA USA Corp. a Delaware corporation located at 3100 West Ray Road, Suite 301, Chandler, Arizona 85226 ("Isola") as follows:

All capitalized terms used but not otherwise defined herein have the meanings given to them in the Security Agreement, the Isola Patent Security Agreement and the Polyclad Patent Security Agreement (each as defined below), as applicable.

WITNESSETH

WHEREAS, Isola and Polyclad Laminates, Inc. ("Polyclad") are parties to a Security Agreement, dated as of December 18, 2006 (the "Security Agreement") in favor of Collateral Agent pursuant to which (i) Isola entered into that certain Patent Security Agreement, dated as of December 18, 2006, as amended (the "Isola Patent Security Agreement") and (ii) Polyclad entered into that certain Patent Security Agreement, dated as of December 18, 2006 (the "Polyclad Patent Security Agreement");

WHEREAS, the Isola Patent Security Agreement was recorded with the United States Patent and Trademark Office on January 9, 2007 at Reel/Frame No. 018731/0465 and the Polyclad Patent Security Agreement was recorded with the United States Patent and Trademark Office on January 9, 2007 at Reel/Frame No. 018731/0378;

WHEREAS, pursuant to the Isola Patent Security Agreement, Isola pledged and granted to Collateral Agent for the benefit of the Secured Parties, and pursuant to the Polyclad Patent Security Agreement, Polyclad pledged and granted to Collateral Agent for the benefit of the Secured Parties a lien on and security interest in and to all of their respective right, title and interest in, to and under all of the following Pledged Collateral of Isola and Polyclad (the "Patent Collateral"):

(a) Patents of Isola and Polyclad listed on Schedule I attached to the Isola Patent Security Agreement or Polyclad Patent Security Agreement, as applicable; and

(b) all Proceeds of any and all of the foregoing (other than Excluded Property);

WHEREAS, Isola and Collateral Agent entered into that certain Amendment No. 1 to Isola Patent Security Agreement, dated as of May 19, 2008 (the "Amendment"), which added certain Patents, listed on Schedule I attached thereto, to the Patent Collateral, and the Amendment was recorded with the United States Patent and Trademark Office on May 19, 2008 at Reel/Frame No. 020963/0194;

WHEREAS, on August 3, 2010, Polyclad merged into Isola and such merger was recorded with the United States Patent and Trademark Office on August 17, 2010 at Reel/Frame No. 024838/0688; and

WHEREAS, Isola and Collateral Agent desire that Collateral Agent terminate and release its lien on and security interest in and to the Patent Collateral, including, without limitation, the Patents set forth in Schedule A attached hereto.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged:

Collateral Agent hereby terminates, releases and discharges fully its lien on and security interest in and to all of the Patent Collateral, including but not limited to the Patents listed on Schedule A hereto, and reassigns and transfers any right, title and interest that Collateral Agent may have in the Patent Collateral to Isola.

Collateral Agent hereby authorizes Isola or Isola's authorized representative to (i) record this Release with the United States Patent and Trademark Office and/or (ii) otherwise record or file this Release in the applicable governmental office or agency.

[SIGNATURE PAGE FOLLOWS]

IN WITNESS WHEREOF, Collateral Agent has caused this Release to be duly executed and delivered by its duly authorized officers as of the date first written above.

UBS AG, STAMFORD BRANCH,
as Collateral Agent

By: ____________________

Name: Mary E. Evans

Title: Associate Director

By: ____________________

Name: Irja R. Otsa

Title: Associate Director

[Signature Page to UBS Release of Security Interest in Patent Collateral]

SCHEDULE A
TO
RELEASE OF SECURITY INTEREST
IN PATENT COLLATERAL

Patents:

Patent No.	Issue Date	Title
4501787	02/26/1985	Flame retardant b-staged epoxy resin prepregs and laminates made therefrom
4665154	05/12/1987	Homogeneous thermoset copolymer from poly (vinyl benzyl ether) and dicyanate ester
4767643	08/30/1988	Method of continuously vacuum impregnating fibrous sheet material
4789770	12/06/1988	Controlled depth laser drilling system
4806596	02/21/1989	Homogeneous thermoset copolymers
5142151	08/25/1992	Method for measuring degree of cure of resin in a composite material and process for making the same
5160567	11/03/1992	System and method for manufacturing copper clad glass epoxy laminates
5334696	08/02/1994	Polyimide resin laminates
5350621	09/27/1994	System of electronic laminates with improved registration properties
5387656	02/07/1995	Substituted cyanoguanidines as curing agents for epoxy resins
5457319	10/10/1995	Process for measurement of the degree of cure and percent resin of glass-fiber-reinforced epoxy resin prepreg
5464658	11/07/1995	System of electronic laminates with improved registration properties
5508328	04/16/1996	Curing epoxy resins using dicy, imidazole and acid
5512381	04/30/1996	Copper foil laminate for protecting multilayer articles
5626774	05/06/1997	Solder mask for manufacture of printed circuit boards
6083855	07/04/2000	Methods of manufacturing voidless resin impregnated webs
6168898	01/02/2001	Positive acting photodielectric composition
6187852	02/13/2001	Fillers for improved epoxy laminates
6242078	06/05/2001	High density printed circuit substrate and method of fabrication
6255039	07/03/2001	Fabrication of high density multilayer interconnect printed circuit boards
6322885	11/27/2001	Talc particles as fillers for improved epoxy laminates
6440567	08/27/2002	Halogen free flame retardant adhesive resin coated composite

Patent No.	Issue Date	Title
6509414	01/21/2003	Epoxy resins, styrene-maleic anhydride copolymer and co-crosslinking agent
6658375	12/02/2003	Compensation model and registration simulation apparatus and method for manufacturing of printed circuit boards
7090924	08/15/2006	Thermosetting resin composition for high performance laminates
7255927	08/14/2007	Laminate composition
7425371	09/16/2008	Thermosetting resin composition for high performance laminates
7507471	03/24/2009	Reducing dusting of epoxy laminates
7521494	04/21/2009	Epoxy resin, sma copolymer and bis-maleimidetriazine resin
4853423	08/01/1989	Curable polyphenylene ether-polyepoxide compositions useful in printed circuit board production
4975319	12/04/1990	Printed circuit board from fibers impregnated with epoxy resin mixture, halogenated bisphenol and polyphenylene ether
5162450	11/10/1992	Curable dielectric polyphenylene ether-polyepoxide compositions
5073605	12/17/1991	Polyepoxide and polyphenylene ether-polyepoxide compositions useful in printed circuit board production
5141791	08/25/1992	Curable polyphenylene ether-polyepoxide compositions from melt processed polyphenylene ethers, and laminates prepared therefrom
5096771	03/17/1992	Fibers impregnated with epoxy resin mixture, brominated bisphenol and polyphenylene ether
5098781	03/24/1992	Thermoplastic film, reinforced hollow glass microsphere reinforced laminates for thin low dielectric constant substrates
5262491	11/16/1993	High performance curable ppo/monomeric epoxy compositions with tin metal salt compatibilizing agent
5108842	04/28/1992	Curable dielectric polyphenylene ether-polyepoxide compositions useful in printed circuit board production
5213886	05/25/1993	Curable dielectric polyphenylene ether-polyepoxide compositions
5362534	11/08/1994	Multiple layer printed circuit boards and method of manufacture
5437914	08/01/1995	Copper-clad laminate and printed wiring board
5557843	09/24/1996	Method of making a circuit board or layer thereof including semi-curing a second adhesive coated on a

Patent No.	Issue Date	Title
		cured first adhesive
5779870	07/14/1998	Method of manufacturing laminates and printed circuit boards
5670250	09/23/1997	Circuit board prepreg with reduced dielectric constant
5545466	08/13/1996	Copper-clad laminate and printed wiring board
5626804	05/06/1997	Roller position controller for a continuous belt press
6618238	09/09/2003	Parallel plate buried capacitor
6584820	07/01/2003	Surface enhanced metal press plates for use in manufacture of laminates and multilayer materials and method of making same
6609294	08/26/2003	Method of bulk fabricating printed wiring board laminates
6436276	08/20/2002	Cathodic photoresist stripping process
6403229	06/11/2002	Cyanate ester based thermoset compositions
6632511	10/14/2003	Manufacture of prepregs and laminates with relatively low dielectric constant for printed circuit boards
6955740	10/18/2005	Production of laminates for printed wiring boards using protective carrier
6768316	07/27/2004	Laser cutting of laminates for electrical insulation testing
7687556	03/30/2010	Flame retardant compositions
5292557	03/08/1994	Electroless Plating Of Substrates

Patent Applications:

Application No.	Filing Date	Title
09928103	8/10/2001	Visible and fluorescent dye containing laminate materials
10310418	12/5/2002	Epoxy resin, styrene-maleic anhydride copolymer and bismaleimide-triazine resin
10314602	12/9/2002	Copolymer of styrene and maleic anhydride comprising an epoxy resin composition and a co-cross linking agent
10858344	6/1/2004	Laminate composition for producing reduced curl flat thin core laminate
11002045	12/3/2004	Copolymer of styrene and maleic anhydride comprising an epoxy resin composition and a co-cross linking agent
10952102	9/28/2004	Low expansion dielectric compositions

Application No.	Filing Date	Title
11269132	11/8/2005	Flame retardant compositions with a phosphorated compound
11634471	12/06/2006	Laminates For High Speed And High Frequency Printed Circuit Boards
11637222	12/11/2006	Copolymer of Styrene and Maleic Anhydride Comprising an Epoxy Resin Composition and A Co-Cross-Linking Agent
07994003	12/21/1992	Mixtures of Dicyandiamide and Substituted Dicyandiamides as Curing Agents for Epoxy Resins
11230318	9/19/2005	Halogen Free Flame Retardant Adhesive Resin Coated Composite
07958625	10/9/1992	Polyphenylene ether/polyepoxide resin system for electric laminates
08084694	6/29/1993	Roller position controller for a continuous belt press